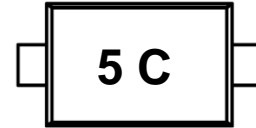


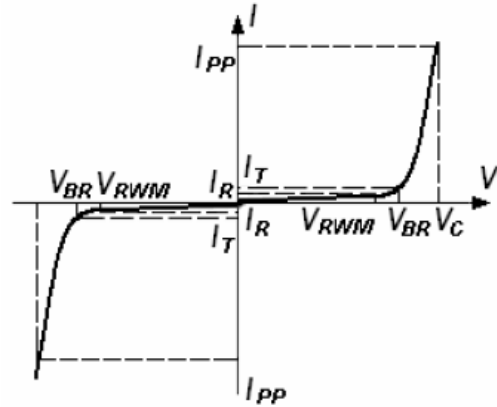
Feature

- 200W peak pulse power per line ($t_p = 8/20\mu s$)
- SOD-523 package
- Replacement for MLV(0603)
- Bidirectional configurations
- Response Time is Typically $< 1\text{ ns}$
- ESD protection $> 16\text{ kV}$
- Low clamping voltage
- RoHS compliant
- Transient protection for data lines to IEC 61000-4-2(ESD) $\pm 15\text{KV(air)}$, $\pm 8\text{KV(contact)}$; IEC 61000-4-4 (EFT) 40A (5/50ns)



Applications

- Cellular phones
- Portable devices
- Digital cameras
- Power supplies

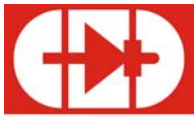


Electrical characteristics per line@25°C (unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Reverse stand-off voltage	V_{RWM}				5	V
Reverse Breakdown voltage	V_{BR}	$I_t = 1\text{mA}$	5.6	6.7	7.8	V
Reverse Leakage Current	I_R	$V_{RWM} = 5\text{V}$ $T=25^\circ\text{C}$			1.0	μA
Junction Capacitance	C_j	$V_R=0\text{V}$ $f = 1\text{MHz}$		32		pF

Absolute maximum rating @25°C

Rating	Symbol	Value	Units
Unidirectional Peak Pulse Power ($t_p=8/20\mu s$)	P_{pp}	200	W
Operating Temperature	T_J	-55 to +150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55 to +150	$^\circ\text{C}$



Typical Characteristics

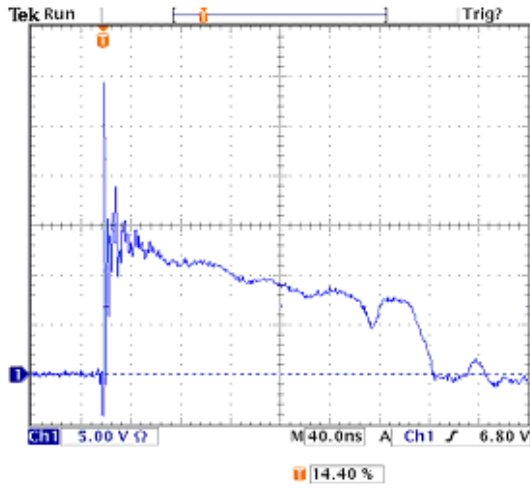


Figure 3. Positive 8 kV Contact per IEC 6100-4-2

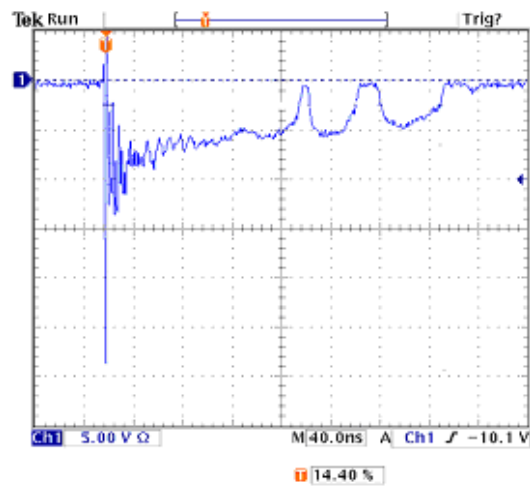
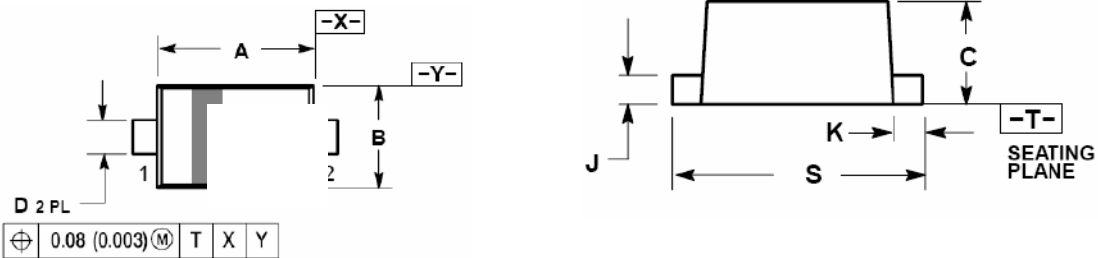


Figure 4. Negative 8 kV Contact per IEC 6100-4-2



Product dimension and pad size

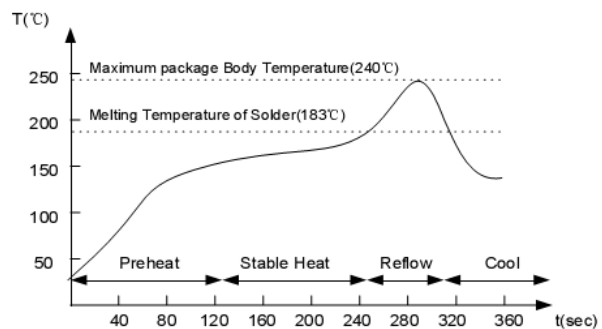


Dim	Millimeters			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.10	1.20	1.30	0.043	0.047	0.051
B	0.70	0.80	0.90	0.028	0.032	0.035
C	0.50	0.60	0.70	0.020	0.024	0.028
D	0.25	0.30	0.35	0.010	0.012	0.014
J	0.07	0.14	0.20	0.0028	0.0055	0.0079
K	0.15	0.20	0.25	0.006	0.008	0.010
S	1.50	1.60	1.70	0.059	0.063	0.067

Reflow Soldering and Rework Recommendations

Recommended reflow methods, Recommended reflow methods: IR, Vapor phase oven, hot air oven.

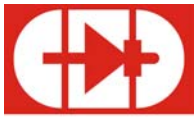
- Devices can be cleaned using standard industry methods and solvents.
- If a device is removed from the board, it should be discarded and replaced with a new device.
- Leaded devices are not designed to be compatible with wave soldering manufacturing operations.
- Lead free reflow curve.



NOTE If reflow temperatures exceed recommended profile, devices may not meet the performance requirements, If the reflow curve can not meet your product, please contact SEMITEL.

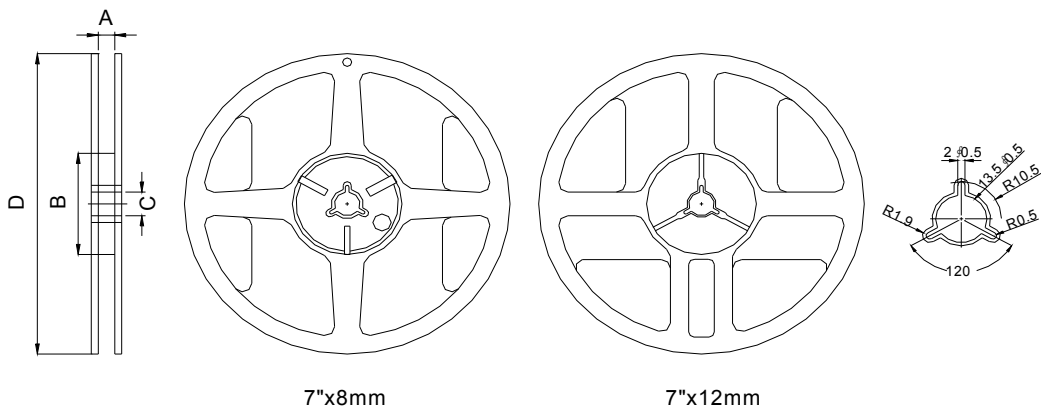
How To Order

Device	Package	Carrier	Marking Code	Standard Quantity
SES5VD523-2B	SOD	Tape	5C	3000pcs



Package Information

Type	A (mm)	B (mm)	C (mm)	D(mm)
7"x8mm	9.0±0.5	60±2	13.5±0.5	178±2



Note: The way of adding the products to the tape is : at intervals of one .

Revision History

Revision	Date	Changes
1.0	2008-7-3	-